

16w3/B



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q78059

Hajime SAIKI, et al.

Allowed: January 5, 2005

Appln. No.: 10/687,626

Group Art Unit: 2854

Confirmation No.: 1784

Examiner: Ren Luo Yan

Filed: October 20, 2003

For: SOLDER PASTE PRINTING METHOD, SOLDER PASTE PRINTING APPARATUS,  
AND METHOD FOR MANUFACTURING A WIRING SUBSTRATE HAVING  
SOLDER-PRINTED LAYERS

**AMENDMENT UNDER 37 C.F.R. § 1.312**

**MAIL STOP ISSUE FEE**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Pursuant to the provisions of 37 C.F.R. § 1.312, please amend the above-identified  
application as follows on the accompanying pages.

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